



Subject: 796

Date: September 19, 2011

TO: Subscribers to UL's Component Recognition Service for: Wiring,  
Printed (ZPMV2, ZPMV3, ZPMV8, ZPMV9)

SUBJECT: Revised Issue of the Standardized Appendix Pages (SAP) for  
Component: Wiring, Printed (ZPMV2, ZPMV3, ZPMV8, ZPMV9)

UL has developed a revised issue of the Standardized Appendix Pages (SAP) for Component: Wiring, Printed (ZPMV2, ZPMV3, ZPMV8, ZPMV9).

The revisions cover updates and improvements to clarify instructions to manufacturers and UL Field Representatives. The sample selection for Follow-Up Test at UL has been revised to specify a consistent sample grouping criterion (based on the ANSI or generic type of the board) and sample selection frequency. These revisions simplify the current selection requirements and thus will help assure better consistency in the application of these requirements. Although the revisions are not expected to significantly increase the number of boards selected for testing at UL in most of the cases, some minor frequency adjustments may be seen, in either direction, based on specific case-by-case situations. An Appendix E was also added to include definitions of common terms that are used throughout the SAP or during inspections.

"Unrecognized" materials are no longer documented in the Appendix pages for sample selection, and those that existed before either were moved or are going to be moved to unlisted component QMTS3 or QMJU3 file volumes where they would be subjected to the sample selection criteria for the corresponding categories. In addition, the move of those "unrecognized" materials is free of charge and there would be no incremental inspection fee charges as a result of the move.

The revised manufacturer specific sample selection and testing information pages, and revised SAP incorporating the changes outlined in this bulletin, will be issued separately by January 31, 2012. Manufacturers must retain and continue using the current SAP, along with the information contained in this bulletin, until the revised SAP dated September 19, 2011 is received.

The SAP revisions reflect current practice, and are effective immediately. The major revisions to the revised edition of the SAP are highlighted below:

#### Appendix A

- Incorporated general SAP template wording, referencing to the UL Mark Surveillance Document as applicable
- Deleted references to factory incoming tests for using subcontractors.
- Updated instructions for inspection of the product regarding board parameters and process
- Updated instructions for multisite processing Updated instructions for flammability only boards

#### **Appendix B**

- Incorporated general SAP template wording
- Revised sample selection instructions by redefining the sample grouping criterion and sample selection frequency
- Reduced the number of smaller boards required for FUS Testing from twelve to six
- Removed unrecognized materials sample selection requirements and guide as all they would be covered under unlisted component file volumes

#### **Appendix C**

- Clarified testing instructions
- Removed the table indicating which PWB types require 56-Day Bond Strength Test, as the same info would be covered in the Sample Selection Guide in Sp. App. B
- Removed the Qualitative Infrared Analysis and the associated data, as all unrecognized materials would be covered under unlisted component file volumes

#### **Appendix D**

- Incorporated general SAP template wording, referencing to the UL Mark Surveillance Document, as applicable
- Updated instructions for multisite processing to describe multisite processor and subcontractor requirements
- Removed the multisite processor info

#### **Appendix E**

- Moved terms and definitions from Appendix A to this new appendix, and made it align with those specified in the Standard.

#### **Special Appendix B**

- Added Special Appendix B to put in Sample Selection Guide, and Index to Footnotes pages

Your Field Representative can assist you with any questions regarding this bulletin or the filing and use of the revised SAP pages.

Any questions concerning the above can be directed to Ms. Crystal Vanderpan by phone: intl. 1+408-754-6584, or e-mail: Crystal.e.Vanderpan@us.ul.com.

Thank you for your continued cooperation with UL's Follow-Up Service Program.

Reviewed by:

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